

Electronic Patent Application Fee Transmittal

Application Number:	10807417								
Filing Date:	23-Mar-2004								
Title of Invention: Microcap wafer bonding apparatus									
First Named Inventor/Applicant Name:	R. Shane Fazzio								
Filer:	Thomas F. Woods								
Attorney Docket Number:	10030899-1								
Filed as Large Entity									
Utility Filing Fees <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 30%;">Description</th> <th style="width: 15%;">Fee Code</th> <th style="width: 15%;">Quantity</th> <th style="width: 15%;">Amount</th> <th style="width: 15%;">Sub-Total in USD(\$)</th> </tr> </thead> </table>					Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)					
Basic Filing:									
Pages:									
Claims:									
Miscellaneous-Filing:									
Petition:									
Patent-Appeals-and-Interference:									
Post-Allowance-and-Post-Issuance:									
Extension-of-Time:									
Extension - 1 month with \$0 paid	1251	1	120	120					

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				120